PTO/SB/08A (08-00)

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Sub	stitute for fo	orm 1449A/PT	0		Complete if Known	970
				Application Number	Unassigned	2
IN	INFORMATION DISCLOSURE			Filing Date	Filed Herewith	0°0
ST	FATEM	ENT BY A	APPLICANT	First Named Inventor	Hui WANG	ಶ್ಮ
				Group Art Unit	Unassigned	77
	use as m	iany sheets a	s necessary)	Examiner Name	Unassigned	
Sheet	1	of	2	Attorney Docket Number	ACMR-001/03US	7

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Examiner	William Leader	Date Considered	9/2003
Signature	MILLIAN LEGGER	Considered	11 44 17

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³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3).

For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. Skind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible.

⁶ Applicant is to place a check mark here if English language Translation is attached.

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					Complete if Known				
Substitute for form 1449B/PTO			0	Application Number	Unassigned	0			
				Filing Date	Filed Herewith	6 4			
INI	INFORMATION DISCLOSURE			First Named Inventor	Hui WANG				
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Sheet	2	of	2	Attorney Docket Number	ACMR-001/03US	200			
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		OTHER PRIOR ART – NON PATENT LITERATURE DOCUMENTS	
Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
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Examiner Signature	William Leader	Date Considered	9/2003	

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INFORMATION DISCLOSUR MITATIO IN AN APPLICATION

(Use several sheets if necessary)

Docket	Number	495152000111
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Application Number 09/837,911

Applicant

Hui WANG

Filing Date April 18, 2001

Mailing Date March 7, 2003

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